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ABSTRACT OF THE DISCLOSURE

There are provided a wiring board, wherein a predetermined wiring section is disposed on an insulation board, and an electromagnetic shielding film is placed at a position close to the wiring section; a semiconductor device, wherein an electromagnetic shielding film is disposed on a surface, on which an integrated circuit of a semiconductor chip has been formed, through an insulative film, a lead is provided on the electromagnetic shielding film through an insulative film, the lead is electrically connected to an external terminal of the semiconductor chip, and the resulting structured material is sealed with a sealing material; and a circuit board for electronic parts composed of a circuit board prepared by forming a plurality of leads on an insulating material, and a conductor disposed on the plurality of leads through an insulating material and reducing a self inductance of the plurality of leads by flowing an eddy current through the conductor. Thus, a technology by which reduction in an inductance of a wiring section disposed in a usual wiring board or that of wiring leads placed in a semiconductor package as well as reduction of inductive cross talk can be achieved. Furthermore, a circuit board for electronic parts by which its characteristic impedance can be easily adjusted in even a field of digital circuits which have been fabricated in an extraordinary number is obtained.